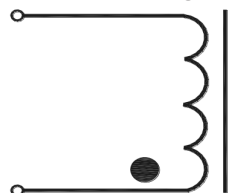


**RoHS
Compliant**



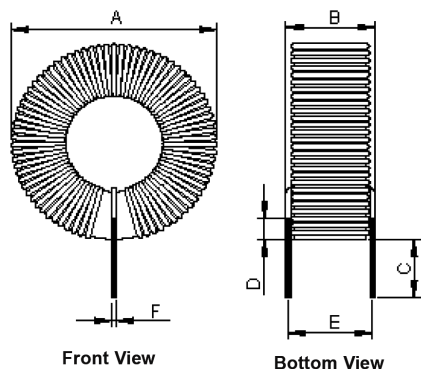
Schematic Diagram



Note:

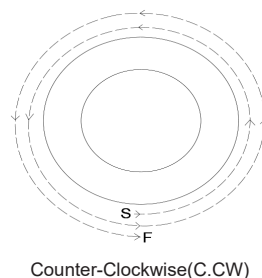
1. Wire UEFN/U Ø1mm (155°C)
2. 77TS (Reference) C.W

Configurations and Dimensions



A	43mm (Max.)
B	16mm (Max.)
C	12.5 ±1mm
D	1mm (Min.)
E	13.5 ±1mm
F	1 ±0.1mm

Winding Structure



Test Data for Mechanical

Test Item	A mm	B mm	C mm	D mm	E mm	F mm
Specification	43 (Max.)	16 (Max.)	12.5 ±1	1 (Min.)	13.5 ±1	1 ±0.1
1	41.62	14.57	12.59	1.75	13.78	1.01
2	41.72	14.6	12.38	1.8	13.82	1.01
3	41.82	14.62	13.01	1.54	13.88	1
4	41.9	14.59	12.75	1.68	13.82	1.02
5	41.75	14.62	13.02	1.75	13.74	1.01
Average	41.76	14.6	12.75	1.7	13.81	1.01

Electrical Characteristics

Inductance : L=560μH ± 15%:at 10kHz/5mA
 DCR Test: : 85mΩ Max at Ta=25°C
 Rated Current : 6.8A Max.
 Temperature rise 40°C Typ.
 Operating Temperature : -55°C to +130°C

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 Farnell.com/multicomp-pro
 sg.element14.com/b/multicomp-pro

Reliability Test

Test Item	Specifications	Test Method and Remarks
Operating temperature range	-55°C to +130°C	Including temperature rise due to self-generated heat.
Storage condition	Ambient temperature : 0°C to 40°C Humidity : Below 70% RH	To maintain the solderability of terminal electrodes, care must be taken to control temperature and humidity in the storage area.
Moisture sensitivity	Appearance : No abnormality : No damage DCR change : Within ±5% Inductance change : Within ±5%	According to J-STD-020B level 3 Test condition : 60°C 60% RH Test duration : 40 hrs Recovery : 1 to 2 hours of recovery under the standard condition after the removal from the test chamber.
Solderability	All termination shall exhibit a continuous solder coating free from defects for a minimum of 95% of the surface area of any individual lead.	According to J-STD-002B Steam aging category : 97°C 98% RH Steam aging duration : 8 hrs Solder : Lead-free solder Solder temperature : 260 ±5°C Dip time : 5 +0 / -0.5s

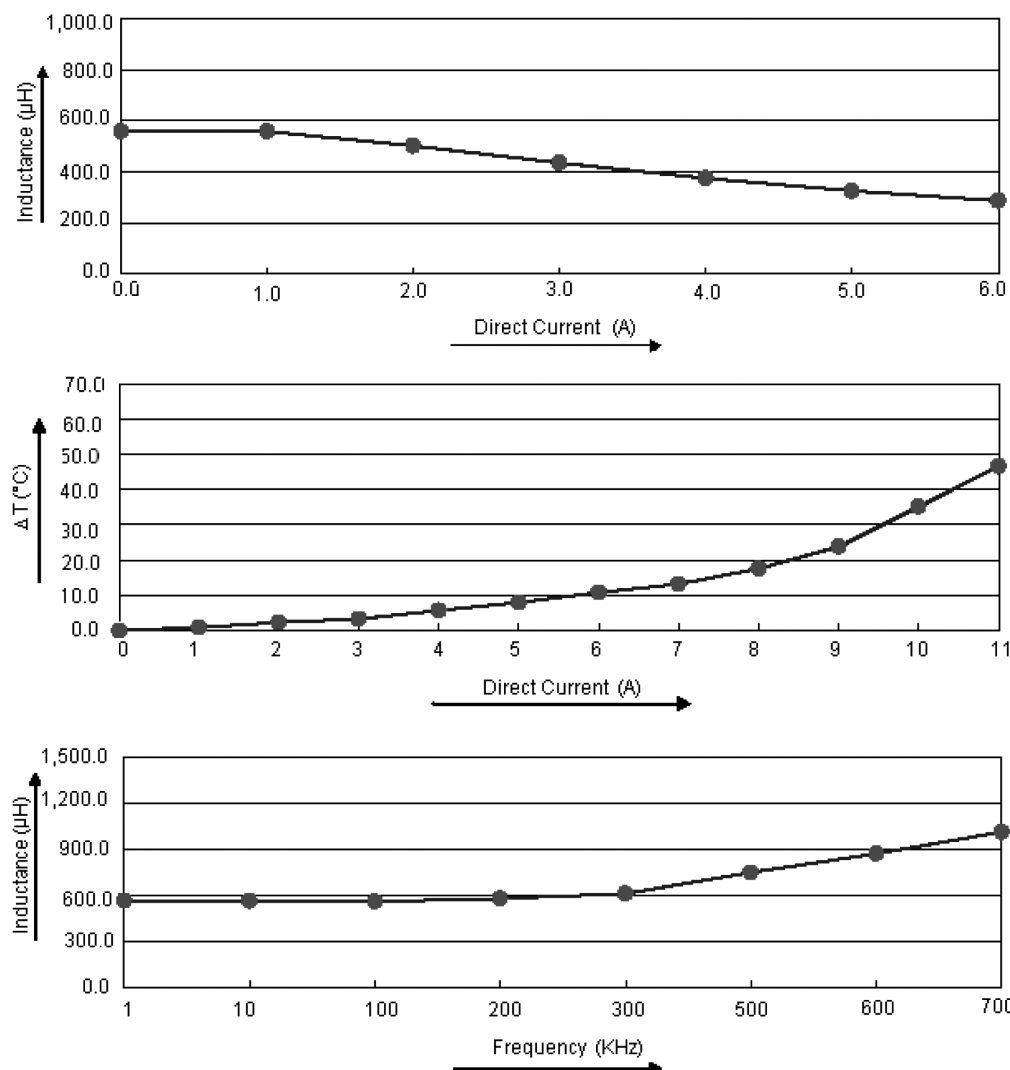
Test Data for Electrical

Test Item	L μH	DCR mΩ	ΔT
Condition	10kHz / 5mA	at 25°C	10kHz / 5mA I _{rms} = 10A
Specification	560 ±15%	77 ±10%	Temperature rise 40°C (Max.)
1	557.2	78.98	OK
2	564.5	77.41	
3	578.55	76.71	
4	580.8	79.07	
5	559.72	77.32	
Average	568.15	77.9	OK

Material List

No.	Item	Material Description
1	Core	T150-75-TAF200 (Red / White)
2	Wire	UEFN/U 1mm (155°C)
3	Solder	Sn99.3% / Cu0.7%

Electric Characteristics



Part Number Table

Description	Part Number
Inductor, 560μH, 15%, 2 Pins	MCAP115018077A-561LU

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